

An Invitation to Join

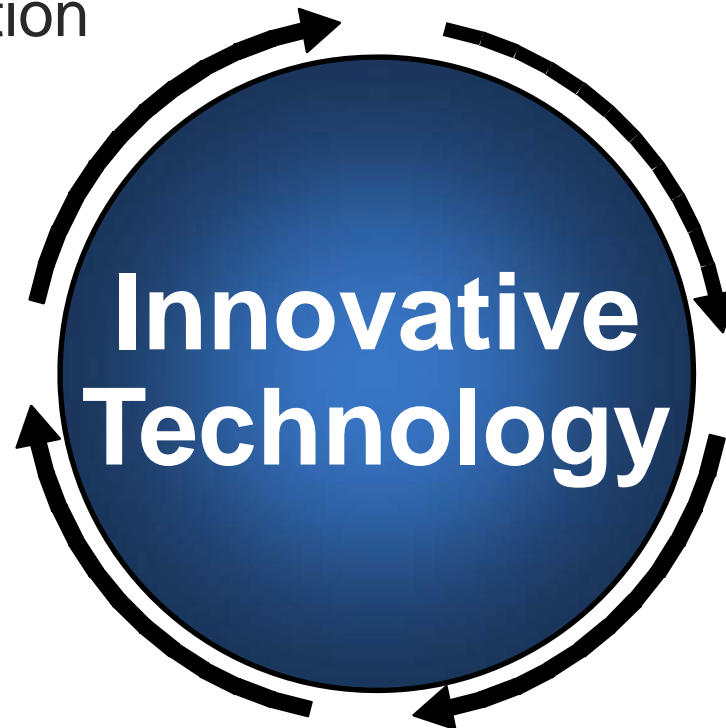


Agenda

- Why industry collaboration?
- Goals of the eBeam Initiative
- Member structure, commitments and cost

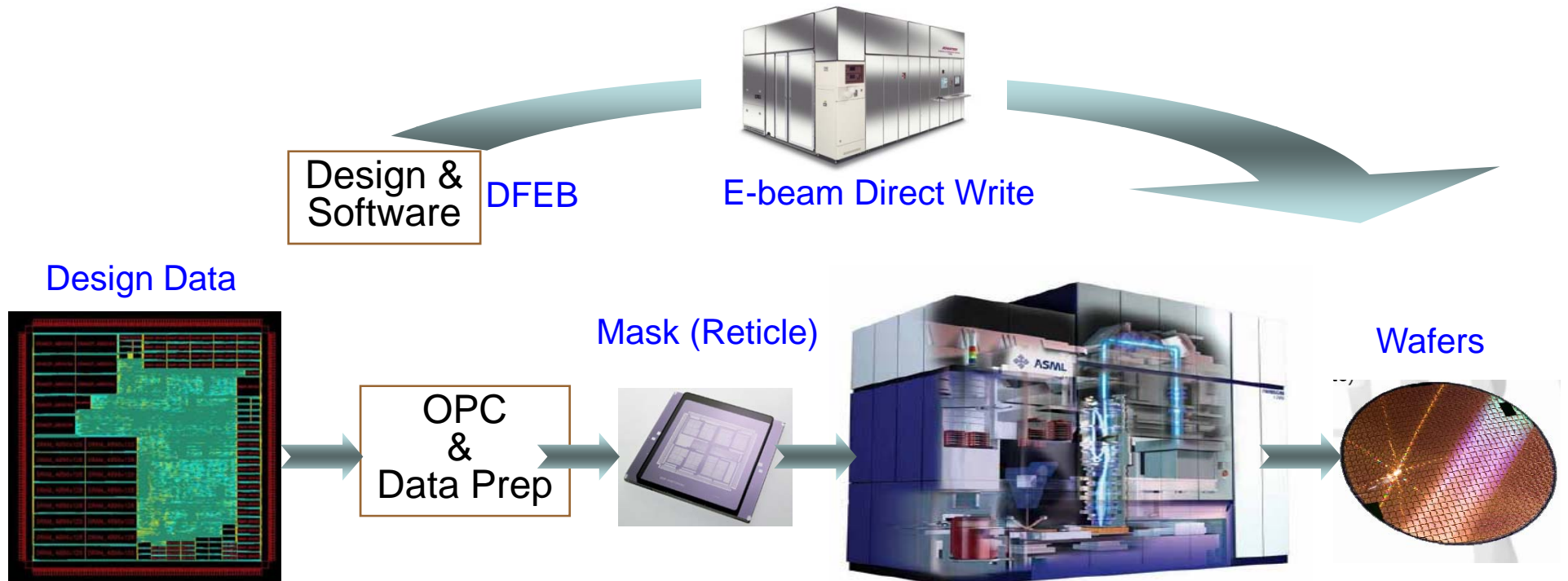
Why Industry Collaboration?

- Accelerates Technology Momentum
- Removes Barriers to Adoption
- Requires leadership



DFEB Technology

Systems Ecosystem Potential



DFEB Adoption Barriers

- Manufacturing accuracy & throughput?
- Equipment ready?
- Design flow ready?
- Path from e-beam to mask based production?
- Qualified design teams?
- Design kits and stencil masks?
- Manufacturing capacity?
- Is it scalable?



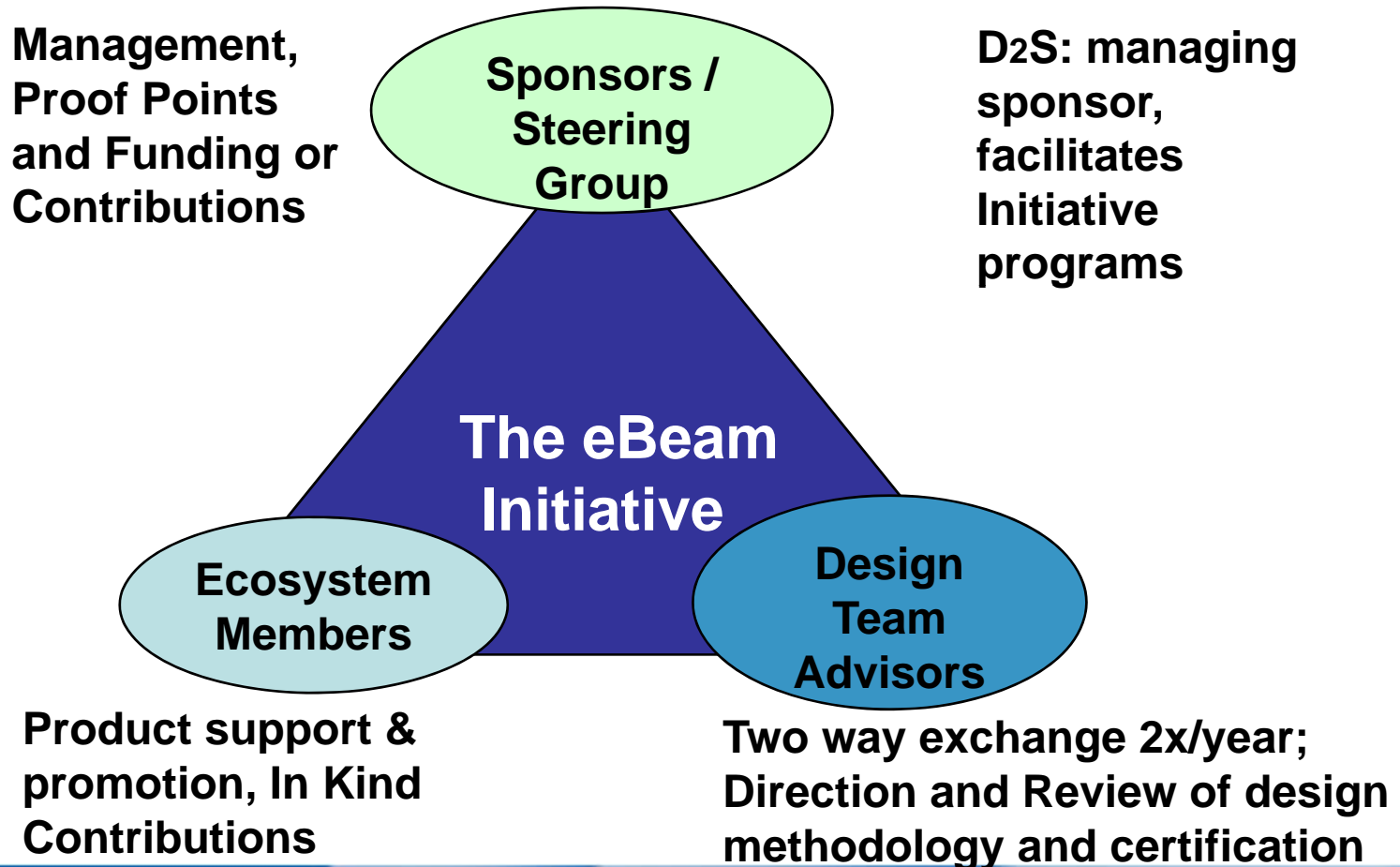
The eBeam Initiative Goals

More Design Starts, Faster Time to Market

Collaborating to:

- Reduce barriers to adoption of DFEB
- Increase the number of customers or customers' customers of DFEB
- Increase investment in multiple DFEB supply chains

The eBeam Initiative Structure





Ecosystem Membership

Benefits:

- Reduces barriers to DFEB adoption
- Increases customers or customers' customers
- Increases investment in DFEB supply chain
- Priority investment from D2S to collaborate on validation of your products in a DFEB solution
- Market leading access vs non-members to the DFEB solution
- Facilitated designer input through the Design Team Advisors

Commitments:

- Attends two annual membership meetings
- Public participation in at least one market education program
- Participation in website
- 3 year commitment from the company
- In kind contributions (no fees) or \$5K annually



Ecosystem In Kind Contributions (No Fees)

This is the goal

Negotiated in each case:

- Methodology:
 - Contributes to and/or reviews methodology guide
 - Sends at least one employee through certification training when available
- Non-commercial product access for validation or proof points (if applicable):
 - Access to 1 license of company's products for validation of the DFEB solution (not commercial chip design)
- Marketing:
 - At least one technical paper e.g. user group, conference paper

Steering Group Membership

Benefits:

- **Reduces barriers to DFEB adoption**
- **Increases customers**
- **Increases investment in DFEB supply chain**
- **Priority investment from D2S to collaborate on your DFEB proof point projects**
- **Influence on Initiative activities through the Steering Group**
- **Enhances your leadership perception and brand promotion**

Commitments:

- **Assigns steering group representative**
- **Attends two annual membership & steering group**
- **Public participation in market education programs (e.g. panels, articles, press releases)**
- **Participation in website including photo of steering group rep**
- **3 year commitment from the company**
- **In kind contributions (no fee) or \$25K annually**



Steering Group In Kind Contributions (No Fees)

This is the goal

Manufacturing & Design Proof points:

- Funds/supports proof points (silicon test chips) at each technology node at 65nm and below
- D2S access to 1 license of company's products for validation of the DFEB solution only (not commercial chip design)

DFEB Certification:

- Sends at least one employee to certification training, when available
- Contributes to methodology guide with content, review or both

Marketing

- Jointly markets proof points (press release, technical paper, presentation, web)

Design Team Advisor Membership

By invitation from Steering Group only

Benefits:

- Reduces barriers to DFEB adoption
- Increases customers or customers' customers
- Increases investment in DFEB supply chain
- Participation provides you with "first to market" access to the DFEB methodology through priority access to the D2S team for knowledge transfer and certification

Contributions:

- Priorities and review of methodology guide and certification projects
- Test cases/designs where possible
- Attends and presents at two annual membership meetings
- Participation in website including photo of sponsor
- 3 year commitment from the company (no fees)

Member Companies & Advisors



ADVANTEST



cādence



Marty Deneroff
D. E. Shaw
Research

DNP
Dai Nippon Printing



FASTRACK
DESIGN



Jack Harding
eSilicon

FUJITSU



MAGMA



Colin Harris
PMC-Sierra



TOPPAN



Riko Radojic
Qualcomm



Jean-Pierre Geronimi
STMicroelectronics